

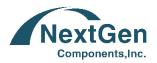
SPECIFICATION SHEET

SPECIFICATION SHEET NO.	N0621- CR0402JC240RS1
DATE	June 21, 2021
REVISION	AO
DESCRIPITION	Thick Film Chip Resistors, 0402 (1005 Metric) Series, L1.00*W0.50*H0.35mm, Tolerance:+/-5%, Resistance 240 ohm, Dissipation 1/16W Max. Operating Temp. Range -55°C ~+155°C Package in Tape/Reel, 10,000pcs/Reel RoHS/RoHS III compliant
CUSTOMER	
CUSTOMER PART NUMBER	
CROSS REF. PART NUMBER	
ORIGINAL PART NUMBER	Aillen CR02JC240R
PART CODE	CR0402JC240RS1

VENDOR APPROVE			
Issued/Checked/Approved	Compone Mandy Xu Yovy you	Compose Cumpos	Low Pore
DATE: June 21, 2021			
CUSTOMER APPROVE			

DATE:

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THICK FILM CHIP RESISTORS 0402 SERIES

MAIN FEATURE

- High Reliability And Stability
- Reduced Size Of Final Equipment
- Lower Assembly Costs
- Higher Component And Equipment Reliability
- RoHS III Compliant And Halogen Free Products

APPLICATION

- Consumer Electrical Equipment
- EDP, Computer Application
- Telecom Application

PART CODE GUIDE



CR	0402	J	С	240R	S	1
1	2	3	4	5	6	7

1) CR: Product code for Thick Film Chip Resistors

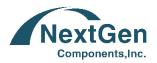
2) 0402: Series Code, 0402 (1005 Metric) Series, Dimensions L1.00*W0.50*H0.35mm

3) J: Resistance Range Tolerance Code, P: Jumper; B: +/-0.1%; D: +/-0.5%; F: +/-1%; J: +/-5%

- 4) C: Package Code, A: 4Kpcs/Reel; B: 5kpcs/Reel; C: 10kpcs/Reel; M: 15kpcs/Reel; D: 10kpcs/10" Reel; E: 20kpcs/10" Reel
- 5) 240R: Resistance value code. 0R: 0ohm; 1R2: 1.2ohm; 20R: 20ohm; 240R: 240ohm; 10K: 10Kohm; 15K: 15 Kohm; 10K5:

10.5Kohm; 100K: 100Kohm; 1M2: 1.2Mohm

- 6) S: SMD type code
- 7) 1: Internal control code, 1~3 digits or letter; Blank: N/A



THICK FILM CHIP RESISTORS 0402 SERIES

DIMENSION (Unit: mm)

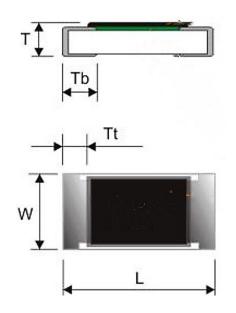
Image for reference



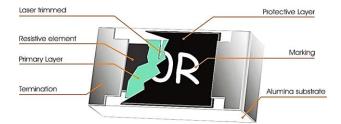


Marking: Blank

0402

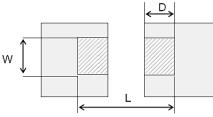


ltem	Dimension
L	1.00±0.05
W	0.50±0.05
Т	0.35±0.05
Тb	0.25±0.10
Τt	0.20±0.10



Resistors Construction For Reference

> Recommended Solder Pad



ltem	Dimension	
W	0.50~0.60	
L	1.40~1.60	
D	0.40~0.60	

NextGen Components, Inc.



THICK FILM CHIP RESISTORS 0402 SERIES

GENERAL ELECTRONICAL CHARACTERISTICS

	Item	Unit	Symbol	Characteristic	Condition
Proc	duct Name		CR	Thick Film Chip Resistors	
	Size		0402	0402 (1005 Metric) Series, Dimensions L1.00*W0.50*H0.35mm	
Resist	tance Range	Ω		240	
Resista	nce Tolerance		J	+/-5%	
TCR	10MΩ≥R > 10Ω	ppm/°C		≤±100	
	R≤10Ω			-200~+400	
Max.	Dissipation	W		1/16	@ Tamb=70°C
Operatin	ng Temperature	°C		-55 ~+155	
Max. Ope	eration Voltage	V		50	@DC or RMS
Max. Ov	erload Voltage	V		100	@DC or RMS

TEST CONDITION FOR JUMPER (0 Ω)

Item	Unit	Symbol	Characteristic	Condition
Power Rating At 70°C	W		1/16	
Max. Resistance	mΩ		50	
Rated Current	А		1.0	
Peak Current	А		2.0	
Operating Temperature	°C		-55 ~+155	

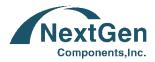
Note

1) This is the maximum voltage that may be continuously supplied to the resistor element, see "IEC publication 60115-8"

2) Max. Operation Voltage : So called RCWV (Rated Continuous Working Voltage) is determined by

RCWV = $\sqrt{Rated Power \times Resistance Value}$ or Max. RCWV listed above, whichever is lower.

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THICK FILM CHIP RESISTORS 0402 SERIES

GENERAL CHARACTERIZATION

Standard values of nominal resistance are taken from the E24 & E96 series for resistors with a tolerance Of +/-0.1%, +/-0.50, +/-1%, +/-5%, The values of the E24/E96 series are in accordance with "IEC publication 60063"

Derating: The power that the resistor can dissipate depends on the operating temperature; see Fig.1

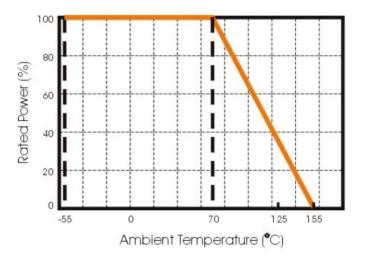
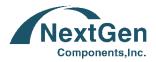


Fig 1 Maximum dissipation in percentage of rated power as a function of the ambient temperature for CR0402

STORAGE AND HANDLING CONDITIONS

1) Products are recommended to be used up within two years since operation date as ensured shelf life. Check solderability in case shelf life extension is needed.

2) To store products with following condition: Temperature : 5 to 40°C Humidity: 20 to 70% relative humidity
3) Don't store products in a corrosive environment such as sulfide, chloride gas, or acid. It may cause oxidization of electrode, which easily be resulted in poor soldering b.To store products on the shelf and avoid exposure to moisture. Don't expose products to excessive shock, vibration, direct sunlight and so on.



THICK FILM CHIP RESISTORS 0402 SERIES

REFLOW SOLDERING CONDITION

The robust construction of chip resistors allows them to be completely immersed in a solder bath of 260 °C for 10 seconds. Therefore, it is possible to mount Surface Mount Resistors on one side of a PCB and other discrete components on the reverse (mixed PCBs). Surface Mount Resistors are tested for solderability at 235 °C during 2 seconds. The test condition for no leaching is 260°C for 30 seconds. Typical examples of soldering processes that provide reliable joints without any damage are given in Fig 2.

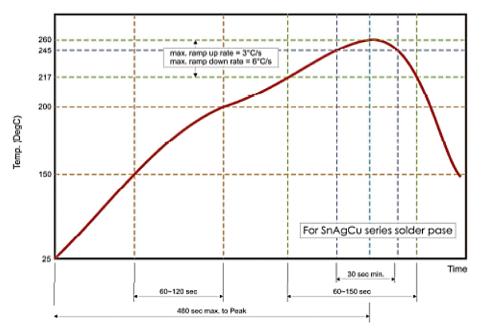


Fig 2. Infrared soldering profile for Chip Resistors

TEST AND REQUIREMENTS

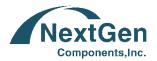
Essentially all tests are carried out according to the schedule of IEC publication 115-8, category LCT/UCT/56(rated temperature range: Lower Category Temperature, Upper Category Temperature; damp heat, long term, 56 days). The testing also meets the requirements specified by EIA, EIAJ and JIS. The tests are carried out in accordance with IEC publication 68, "Recommended basic climatic and mechanical robustness testing procedure for electronic components" and under standard atmospheric conditions according to IEC 60068-1, subclause 5.3. Unless otherwise specified, the following value supplied Temperature: 15 °C to 35 °C. Relative humidity: 45% to 75%. Air pressure: 86kPa to 106 kPa (860 mbar to 1060 mbar). All soldering tests are performed with midly activated flux.



THICK FILM CHIP RESISTORS 0402 SERIES

TEST METHOD AND REQUIREMENT

TEST	PROCEDURE / TEST METHOD	REQUIREMENT		
			0Ω	
Electrical Characteristics JISC5201-1: 1998 Clause 4.8	- DC resistance values measurement - Temperature Coefficient of Resistance (T.C.R) Natural resistance change per change in degree centigrade. $\frac{R_2 - R_1}{R_1(t_2 - t_1)} \times 10^6 \text{ (ppm/°C)} t_1 : 20°C+5°C-1°C; t_2 : -55°C \text{ or } +155°C$ R1 : Resistance at reference temperature (20°C+5°C/-1°C) R2 : Resistance at test temperature (-55°C or +155°C)	Within the specified tolerance. Refer to "QUICK REFERENCE DATA"	<50mΩ	
Resistance to soldering heat(R.S.H) JISC5201-1:1998 Clause 4.18	Un-mounted chips completely immersed for 10±1 second in a SAC solder bath at 260°C±5°C	5%: ΔR/Rmax. ±(1%+0.05Ω) 1%: ΔR/Rmax. ±(0.5%+0.05Ω) no visible damage	<50mΩ	
Solderability JISC5201-1: 1998 Clause 4.17	5201-1: 1998 for 2±0.5 second in a SAC solder bath at visi		ing and no	
Temperature cycling JISC5201-1: 1998 Clause 4.19	30 minutes at -55°C±3°C, 2~3 minutes at 20°C+5°C-1°C, 30 minutes at +155° C±3°C, 2~3 minutes at 20°C+5°C-1°C, total 5 continuous cycles	5%: ΔR/Rmax. ±(1%+0.05Ω) 1%: ΔR/Rmax. ±(0.5%+0.05Ω) no visible damage	<50mΩ	
High Temperature Exposure MIL-STD-202 method 108	1000+48/-0 hours; without load in a temperature chamber controlled 155±3°C	5%: ΔR/Rmax. \pm (2%+0.1Ω) 1%: ΔR/Rmax. \pm (1%+0.1Ω) no visible damage	<50mΩ	
Bending strength JISC5201-1: 1998 Clause 4.33	Resistors mounted on a 90mm glass epoxy resin PCB(FR4), bending once 3mm for 10sec, 5mm for CR02	5%: ΔR/Rmax. ±(1%+0.05Ω) 1%: ΔR/Rmax. ±(1%+0.05Ω) no visible damage	<50mΩ	



THICK FILM CHIP RESISTORS 0402 SERIES

TEST METHOD AND REQUIREMENT

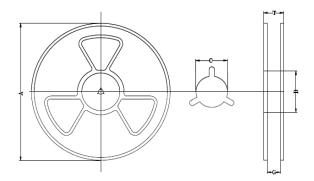
TEST	PROCEDURE / TEST METHOD	REQUIREMENT	
		Resistor	0Ω
Adhesion JISC5201- 1: 1998 Clause 4.32	Pressurizing force: 5N, Test time: 10±1sec.	No remarkable damage or rem terminations	oval of the
Short Time Overload (STOL) JISC5201-1: 1998 Clause 4.13	2.5 times RCWV or max. overload voltage, for 5seconds	5%: ΔR/Rmax. ±(2%+0.05Ω) 1%: ΔR/Rmax. ±(1%+0.05Ω) no visible damage	<50mΩ
Load life in Humidity JISC5201-1: 1998 Clause 4.24	1000 +48/-0 hours, loaded with RCWV or Vmax in humidity chamber controller at $40^{\circ}C \pm 2^{\circ}C$ and $90^{\sim}95\%$ relative humidity, 1.5hours on and 0.5 hours off	5%: ΔR/Rmax. \pm (2%+0.1Ω) 1%: ΔR/Rmax. \pm (1%+0.1Ω) no visible damage	<50mΩ
Load life (endurance) JISC5201-1: 1998 Clause 4.25	1000 +48/-0 hours, loaded with RCWV or Vmax in chamber controller 70±2°C, 1.5 hours on and 0.5 hours off	5%: ΔR/Rmax. \pm (3%+0.1Ω) 1%: ΔR/Rmax. \pm (1%+0.1Ω) no visible damage	<50mΩ
Insulation Resistance JISC5201-1: 1998 Clause 4.6	Apply the maximum overload voltage (DC) for 1minute	R≧10GΩ	
Dielectric Withstand Voltage JISC5201-1: 1998 Clause 4.7	Apply the maximum overload voltage (AC) for 1 minute	No breakdown or flashover	



THICK FILM CHIP RESISTORS 0402 SERIES

REEL DIMENSION (Unit: mm)

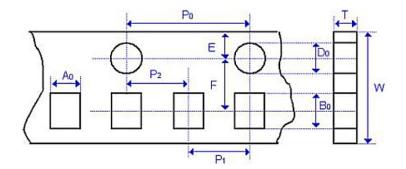
7": 10,000Ppcs/Reel; 10": 20,000pcs/Reel; 13": 40,000pcs/Reel



Code	Dimension 7"	Dimension 10"	Dimension 13"
А	178.0+/-2.0	254.0+/-2.0	33.0+/-2.0
В	60.0 +/-1.0	100 +/-1.0	100+/-1.0
С	13.0+/-0.20	13.0+/-0.20	13.0+/-0.20
Т	9.0+/-0.50	9.0+/-0.5	9.0+/-0.5

TAPE DIMENSION (Unit: mm)

Paper Tape, 2 mm Pitch



Code	Dimension
A 0	0.70+/-0.10
В 0	1.20+/-0.10
Т	0.40+/-0.05
К О	-
W	8.00+/-0.30
P 0	4.00+/-0.10
10xP 0	40.0+/-0.20
P 1	2.00+/-0.10
P2	-
D 0	1.50+/-0.10
D 1	-
E	1.75+/-0.10
F	3.50+/-0.20
	-

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